
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Soon et al.

Attorney Docket No.:
NSC1P296/P05887

Application No.: NEW

Examiner: UNASSIGNED

Filed: HEREWITH

Group: UNASSIGNED

Title: ULTRA-LOW LOOP WIRE BONDING

**INFORMATION DISCLOSURE STATEMENT
37 CFR §§1.56 AND 1.97(b)**

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

The references listed in the attached PTO Form 1449, copies of foreign patents and other documents are attached, may be material to examination of the above-identified patent application. Applicants submit these references in compliance with their duty of disclosure pursuant to 37 CFR §§1.56 and 1.97. The Examiner is requested to make these references of official record in this application.

This Information Disclosure Statement is not to be construed as a representation that a search has been made, that additional information material to the examination of this application does not exist, or that these references indeed constitute prior art.

This Information Disclosure Statement is: (i) filed within three (3) months of the filing date of the above-referenced application, (ii) believed to be filed before the mailing date of a first Office Action on the merits, or (iii) believed to be filed before the mailing of a first Office Action after the filing of a Request for Continued Examination under §1.114. Accordingly, it is believed that no fees are due in connection with the filing of this Information Disclosure Statement. However, if it is determined that any fees are due, the Commissioner is hereby authorized to charge such fees to Deposit Account 500388 (Order No. NSC1P296).

Respectfully submitted,

BEYER WEAVER & THOMAS, LLP



Phillip P. Lee

Registration No. 46,866

P.O. Box 778
Berkeley, CA 94704-0778

Form 1449 (Modified) Information Disclosure Statement By Applicant (Use Several Sheets if Necessary)	Atty Docket No.	Application No.:
	NSC1P296/P05887	NEW
	Applicant:	
	Soon et al.	
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U.S. Patent and Published Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
	A1	5,328,079	07/12/1994	Mathew et al.			
	A2	5,408,127	4/18/95	Mostafazadeh			
	A3	4,818,895	4/4/89	Kaufman			
	A4	5,735,030	4/7/98	Orcutt			
	A5	6,399,421	06/02	Han et al.			
	A6	5,463,253	10/95	Waki et al.			
	A7	6,437,429	08/02	Wu et al.			
	A8	6,118,184	09/00	Ishio et al.			
	A9	5,471,369	11/95	Honda et al.			
	A10	2002/0137327	09/02	Arakawa			
	A11	5,545,922	08/96	Golwalker et al.			
	A12	6,353,265	03/02	Michii			

Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
							Yes	No
	B1	WO02/08257	10/17/02	WIPO				
	B2	EP0753891	1/15/97	EPO				

Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
	C1	John Barber, "Plastic Packaging and the Effects of Surface Mount Soldering Techniques," Microchip Technology, Inc., 12 pages, 1995
	C2	Lai et al., Nordic Electronic Packaging Guideline, Chapter A, printed from: http://www.extra.ivf.se/mgl/A-WireBonding/ChapterA.htm , on March 16, 2004, 25 Pages
	C3	Prof. Daniel F. Baldwin, "Fundamentals of IC Assembly," McGraw-Hill, Chapter. 9, pages 342-353, 2001
	C4	Semiconductor Packaging Assembly Technology, printed from www.national.com , 8 pages, 1999

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	C5	Nakanishi et al., "Development of High Density Memory IC Package by Stacking IC Chips," Abstract No. XP000624986, IEEE, Vol. Conf. 45, Pages 634-640 (1995)
	C6	Patent Abstract of Japan, Pub No. 63219131, Pub Date 9/12/88, 2 Pages
Examiner		Date Considered

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.